

L Number	Hits	Search Text	DB	Time stamp
1	1204	IC with (bonding adj pads)	USPAT; EPO; JPO; DERWENT; USOCR	2004/10/25 09:19
2	1	(IC with (bonding adj pads)) and (inspect\$3 adj pads)	USPAT; EPO; JPO; DERWENT; USOCR	2004/10/25 09:20
4	27	(inspection adj pad) and IC	USPAT; EPO; JPO; DERWENT; USOCR	2004/10/25 09:21
5	19	(inspection adj pad) and wafer	USPAT; EPO; JPO; DERWENT; USOCR	2004/10/25 09:30
6	2	("6100117"   "6109530").PN.	USPAT	2004/10/25 09:32
7	104	inspection adj pads	USPAT; EPO; JPO; DERWENT; USOCR	2004/10/25 09:35
8	2	("6100117"   "6109530").PN.	USPAT	2004/10/25 09:36
3	148	inspection adj pad	USPAT; EPO; JPO; DERWENT; USOCR	2004/10/25 09:46
9	3	("5644331"   "6127998"   "6184849").PN.	USPAT	2004/10/25 09:43
10	16	wafer and (IC adj device) and pads and inspect\$3 and connection and probe	USPAT; EPO; JPO; DERWENT; USOCR	2004/10/25 09:52
11	354	IC and (buffer adj area)	USPAT; EPO; JPO; DERWENT; USOCR	2004/10/25 09:52
12	40	(IC and (buffer adj area)) and pads	USPAT; EPO; JPO; DERWENT; USOCR	2004/10/25 09:58
13	6	("5760643"   "5969538"   "5986320"   "5990695"   "6127729"   "6356095").PN.	USPAT	2004/10/25 09:54
14	4	("5241266"   "5399505"   "5648661"   "6046600").PN.	USPAT	2004/10/25 09:54
15	27	("4956602"   "5241266"   "5278494"   "5279975"   "5286656"   "5291025"   "5313158"   "5315241"   "5334857"   "5366906"   "5371390"   "5389556"   "5389873"   "5390131"   "5391984"   "5399505"   "5424651"   "5446395"   "5457400"   "5461328"   "5489538"   "5532174"   "5534786"   "5557573"   "5608335"   "5619462"   "5648661").PN.	USPAT	2004/10/25 09:55
16	4	("4956602"   "4961053"   "5307010"   "5315241").PN.	USPAT	2004/10/25 09:56
17	107	324/763-765.ccls. and pads and buffer	USPAT; EPO; JPO; DERWENT; USOCR	2004/10/25 09:59
18	2	("6304098"   "6515501").PN.	USPAT	2004/10/25 10:02